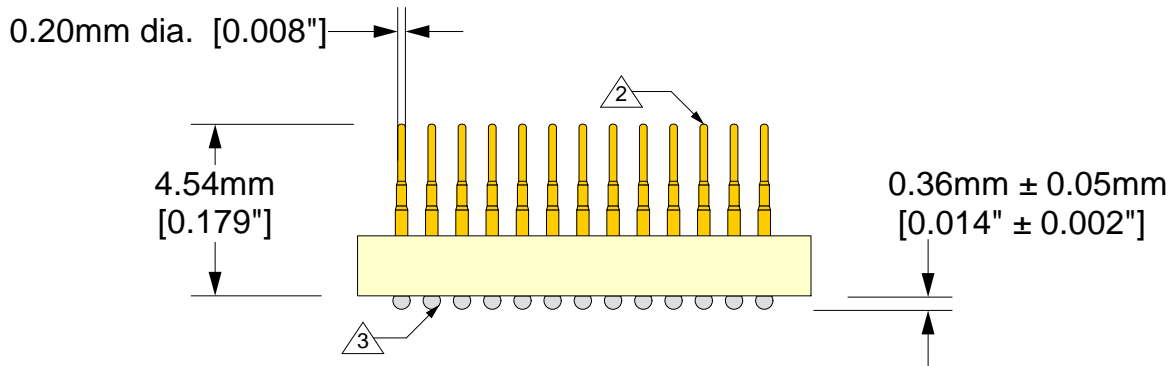


**Top View**




**Side View**

- △1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]  
FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Non clad. (RoHS)
- △2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- △3 Solder Balls: Sn96.5Ag3.0Cu0.5

**Description:** Giga-snaP BGA SMT Foot

130 position (0.8mm pitch) gold plated female pins to SMT solder balls (BGA type). Pin assignment 1:1.

**Tolerances:** diameters ±0.03mm [±0.001"], PCB perimeters ±0.18mm [±0.007"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

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	<p>Drawing: M.A. Fedde</p>	<p>Date: 12/22/08</p>	<p>File: SF-BGA130A-B-61F Dwg</p>	<p>Modified: 07/02/14</p>